

Claims

1. (currently amended) A structure pad for applying photoresist to a surface of a workpiece comprising:

a transfer layer of polydimethylsiloxane with ~~for receiving a separable~~
~~coating of photoresist for in liquid form and applying the coating of photoresist in~~
~~liquid form to a surface of the workpiece; and~~
a cushion layer adjacent attached to the transfer layer and providing
flexible support for the transfer layer.

2. (presently amended) The structure pad of claim 1 further comprising a stiffener
layer adjacent attached to the cushion layer.

3. (presently amended) The structure pad of claim 1 wherein the cushion layer is
silicone rubber.

4. (withdrawn) A method of applying a photoresist comprising the steps of:
applying a liquid photoresist to transfer pad having a transfer layer of
polydimethylsiloxane;
curing the photoresist to form a loaded resist transfer pad ;
pressing the loaded resist transfer pad against a surface of a workpiece;
and
peeling the transfer pad off of the surface leaving a coating of photoresist
adhering to the surface.

5. (withdrawn) The method of claim 4 wherein the workpiece is a slider.

6. (withdrawn) The method of claim 5 wherein the transfer pad further comprises
a cushion layer attached to the transfer layer of polydimethylsiloxane providing
flexible support for the transfer layer.

7. (withdrawn) The method of claim 6 wherein the cushion layer is silicone rubber.

8. (withdrawn) The method of claim 5 further comprising the step of placing the slider in a pallet prior to the pressing step and wherein the step of pressing further comprises the steps of :

 placing the loaded resist transfer pad onto a cover-tape that is larger than the loaded resist transfer pad; and

 urging the loaded resist transfer pad and a section of the cover-tape against the slider and the pallet.

9. (withdrawn) The method of claim 8 wherein the step of pressing further comprising the step of cutting the cover-tape to allow a section of the cover-tape to move with the slider and the pallet prior to the peeling step.

10. (withdrawn) The method of claim 5 wherein the step of pressing further comprises the steps of :

 placing the loaded resist transfer pad onto a press plate of a laminator; and

 moving the press plate to press the loaded resist transfer pad against the workpiece surface.

11. (new) The structure of claim 1 wherein the transfer layer is approximately from 10 to 100 microns thick.

12. (new) The structure of claim 1 wherein the cushion layer is approximately from 0.5 to 3.0 mm thick.

13. (new) The structure of claim 1 wherein the cushion layer is silicone rubber approximately 0.5 to 3.0 mm thick.

14. (new) The structure of claim 2 wherein the stiffener layer is approximately 0.1 to 1.0 mm thick.

15. (new) The structure of claim 1 further comprising a cover-tape attached to the cushion layer opposite to the layer of photoresist, the cover-tape being larger in area than the cushion layer and extending beyond at least first and second edges of the cushion layer.

16. (new) The structure of claim 1 further comprising a stiffener layer attached to the cushion layer, and a cover-tape attached to the stiffener layer opposite to the layer of photoresist.

17. (new) A structure for applying photoresist to a surface of a workpiece comprising:

a cover-tape; and

at least two photoresist pads disposed on the cover-tape, the photoresist pads comprising a polymer layer with a coating of photoresist on a first surface of the polymer layer, and a cushion layer adjacent to a second surface of the polymer layer opposite the coating of photoresist.

18. (new) The structure of claim 17 wherein the polymer layer is polydimethylsiloxane.

19. (new) The structure of claim 17 wherein the photoresist pads further comprise a stiffener layer attached to the cushion layer.

20. (new) The structure of claim 17 wherein the photoresist pads further comprise a stiffener layer attached to the cushion layer.

21. (new) The pad of claim 17 wherein the cushion layer is silicone rubber.

22. (new) The structure of claim 17 wherein the cover-tape and photoresist pads are formed into a roll.

23. (new) The structure of claim 17 wherein the photoresist pads are sequentially disposed on the cover-tape so that unrolling the roll sequentially exposes the photoresist pads.